

SOT2303-1

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.9 mm body

5 August 2026

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	H-PQFN32
Package style descriptive code	H-PQFN (thermal enhanced - plastic quad flat non-lead)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-07-2026
Manufacturer package code	98ASA02293D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
seated height	0.8	0.9	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	



H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm
x 0.9 mm body

2 Package outline

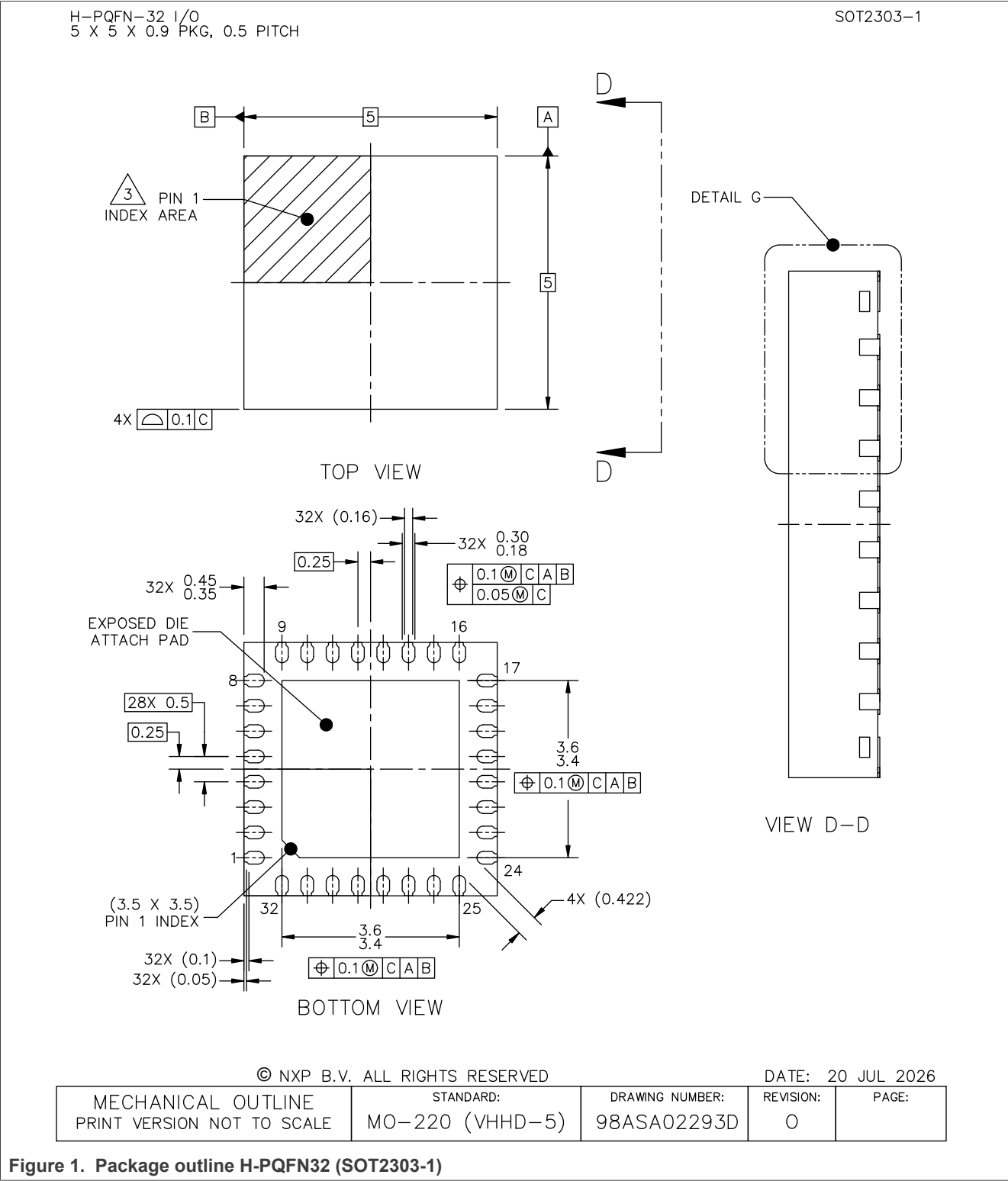
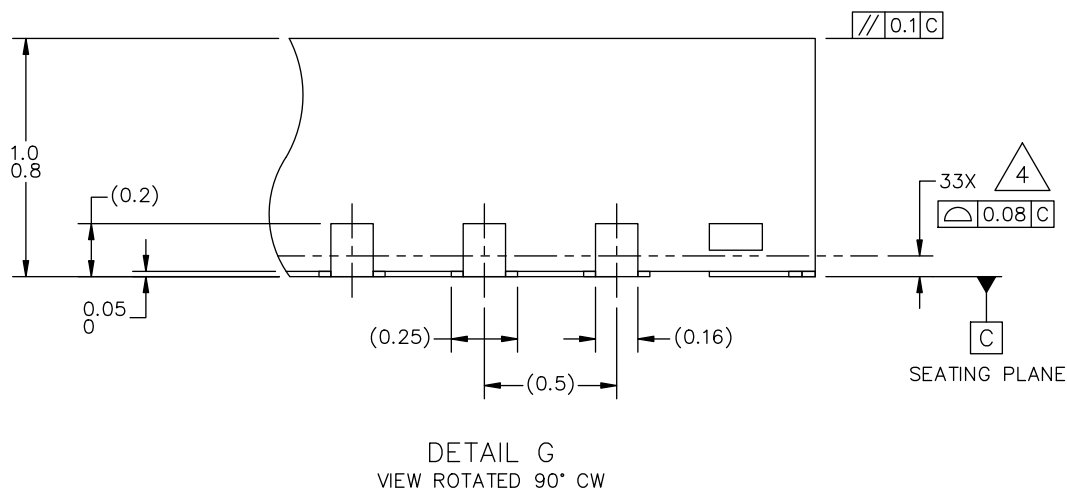


Figure 1. Package outline H-PQFN32 (SOT2303-1)

H-PQFN-32 I/O
5 X 5 X 0.9 PKG, 0.5 PITCH

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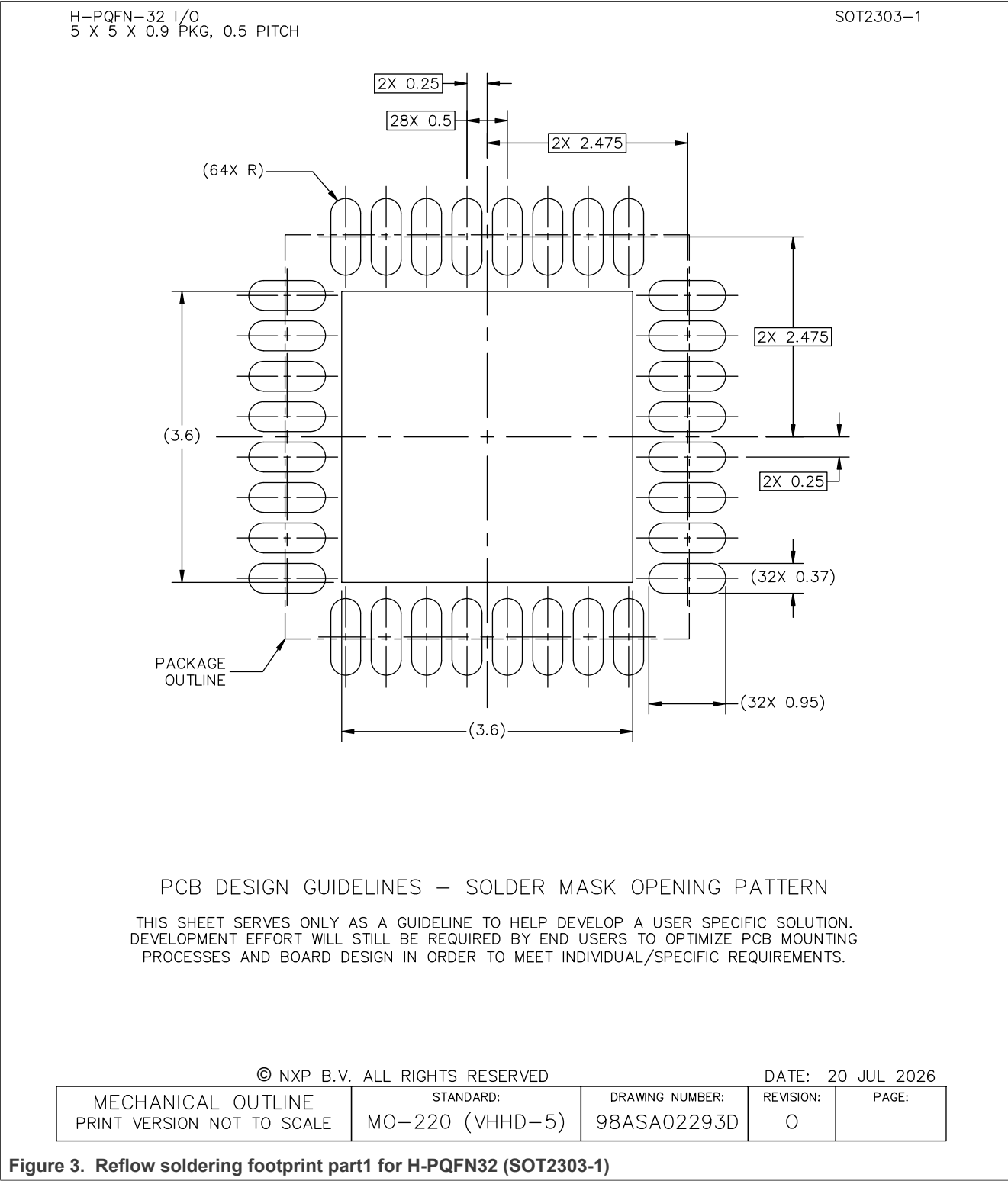


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Figure 2. Package outline detail G of H-PQFN32 (SOT2303-1)

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm
x 0.9 mm body

3 Soldering



H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm
x 0.9 mm body

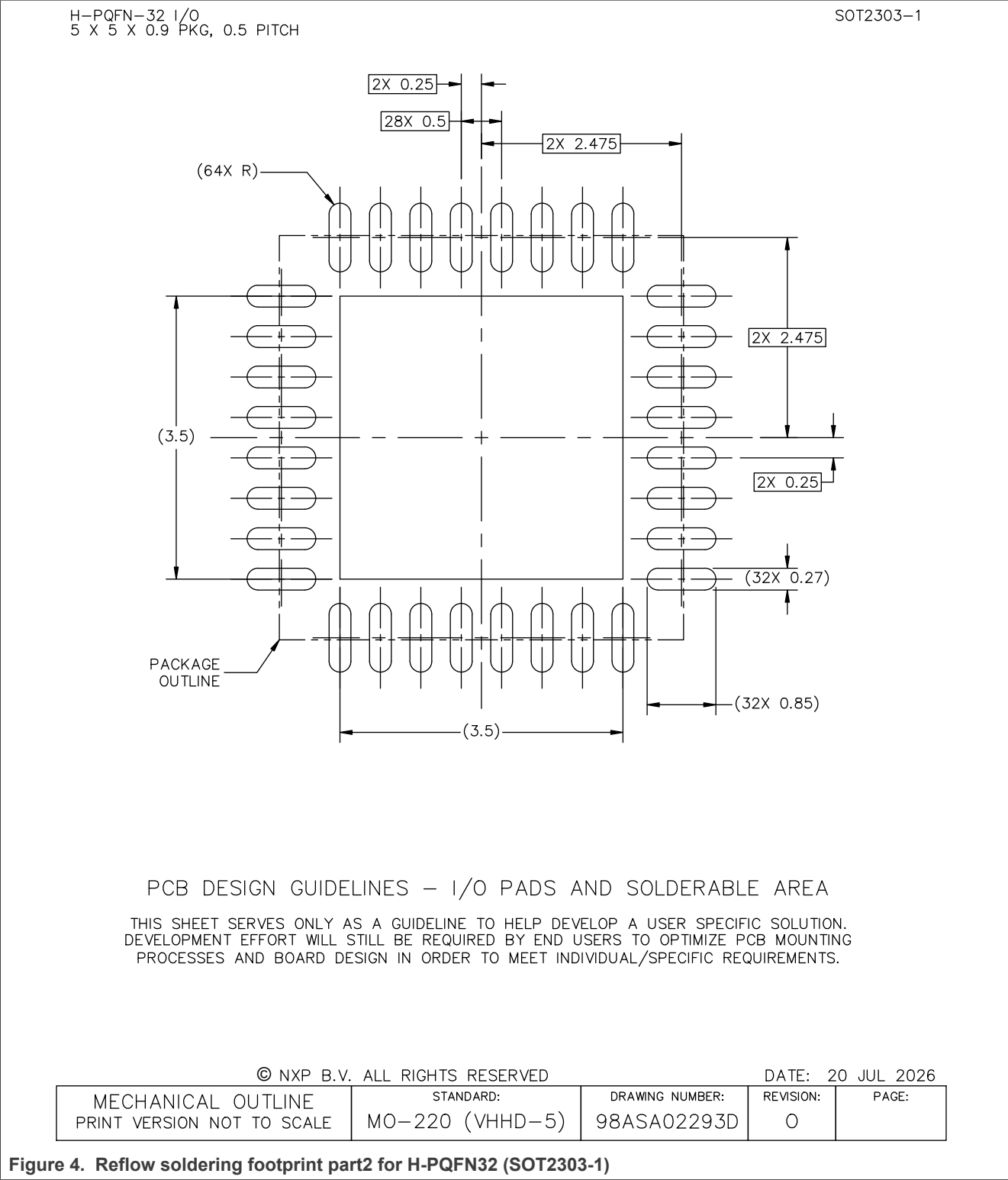
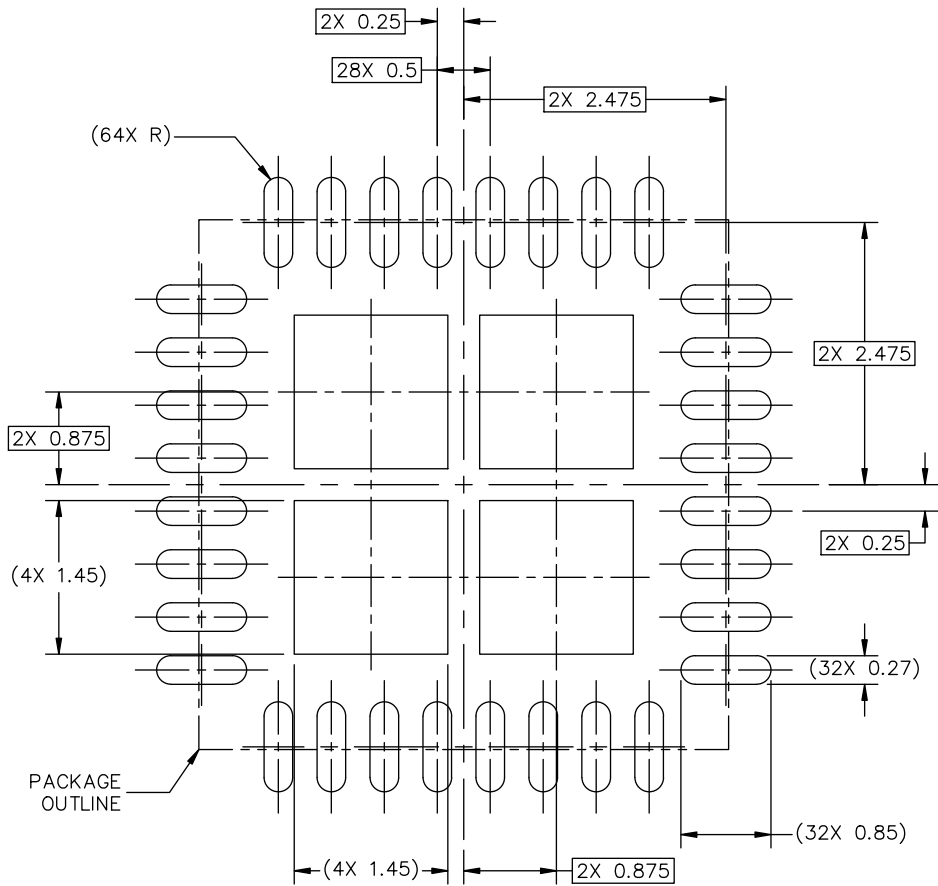


Figure 4. Reflow soldering footprint part2 for H-PQFN32 (SOT2303-1)

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm
x 0.9 mm body

H-PQFN-32 I/O
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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION.
DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING
PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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Figure 5. Reflow soldering footprint part3 for H-PQFN32 (SOT2303-1)

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm
x 0.9 mm body

H-PQFN-32 I/O
5 X 5 X 0.9 PKG, 0.5 PITCH

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- NOTES:
- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. PIN 1 FEATURE, SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
 - 5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note H-PQFN32 (SOT2303-1)

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